Updates from EVM:
R24, R15, L1, L2
add J19 jumper

Tested: See Test and Thermal reports
Design Notes:
1.  TOLER = VREF
2.  TRIPSEL = VOLT
3.  OSSEL = 3.3V BAS
4.  N2 = Volt / 18
5.  FLOW = 40 mA on turn-on of the IC.
6.  TRIFEN & TRIF, pin 24 = TRIFB is used for remote temperature sensing.
7.  TRIFB is an open drain output alarm for the TRIF pin. If remote temperature sensing is not needed, leave both pins as no connects.

The circuit diagram shows various components such as resistors (R1 to R25) and capacitors (C1 to C9) connected to different pins. The diagram also includes labels for pins and components like TP28, TP29, and TP30. The diagram is a schematic representation of the TP51621 2 phase, 48A EVM by Texas Instruments.
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